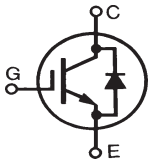
IXYS

GenX3™ 600V IGBT w/ Diode

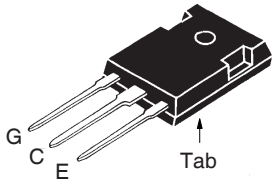
IXGH56N60B3D1

V_{CES} = 600V
I_{C110} = 56A
$V_{CE(sat)}$ ≤ 1.80V

Medium-Speed-Low-Vsat PT
IGBT 5-40kHz Switching



TO-247



G = Gate C = Collector
E = Emitter Tab = Collector

Symbol	Test Conditions	Maximum Ratings	
V_{CES}	T_J = 25°C to 150°C	600	V
V_{CGR}	T_J = 25°C to 150°C, R_{GE} = 1MΩ	600	V
V_{GES}	Continuous	±20	V
V_{GEM}	Transient	±30	V
I_{C110}	T_C = 110°C	56	A
I_{CM}	T_C = 25°C, 1ms	350	A
SSOA (RBSOA)	V_{GE} = 15V, T_{VJ} = 125°C, R_G = 5Ω Clamped Inductive Load	I_{CM} = 150 @ $V_{CE} \leq V_{CES}$	A
P_C	T_C = 25°C	330	W
T_J		-55 ... +150	°C
T_{JM}		150	°C
T_{stg}		-55 ... +150	°C
T_L	Maximum Lead Temperature for Soldering	300	°C
T_{SOLD}	1.6 mm (0.062in.) from Case for 10s	260	°C
M_d	Mounting Torque	1.13/10	Nm/lb.in.
Weight		6	g

Features

- Optimized for Low Conduction and Switching losses
- Square RBSOA
- Anti-Parallel Ultra Fast Diode
- International Standard Package

Advantages

- High Power Density
- Low Gate Drive Requirement

Applications

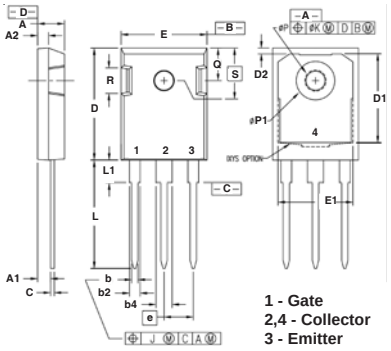
- Power Inverters
- UPS
- Motor Drives
- SMPS
- PFC Circuits
- Battery Chargers
- Welding Machines
- Lamp Ballasts

Symbol	Test Conditions (T_J = 25°C, Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
$V_{GE(th)}$	I_C = 250μA, V_{CE} = V_{GE}	3.0		5.0	V
I_{CES}	V_{CE} = V_{CES}, V_{GE} = 0V			300	μA
	T_J = 125°C			2	mA
I_{GES}	V_{CE} = 0V, V_{GE} = ±20V			±100	nA
$V_{CE(sat)}$	I_C = 44A, V_{GE} = 15V, Note 1		1.49	1.80	V
	T_J = 125°C		1.47		V

© 2014 IXYS CORPORATION, All Rights Reserved

Symbol	Test Conditions (T_J = 25°C Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
g_{fs}	I_C = 44A, V_{CE} = 10V, Note 1	36	60		S
C_{ies}	V_{CE} = 25V, V_{GE} = 0V, f = 1MHz		3950		pF
C_{oes}			220		pF
C_{res}			56		pF
$Q_{g(on)}$	I_C = 40A, V_{GE} = 15V, V_{CE} = 0.5 • V_{CES}		138		nC
Q_{ge}			25		nC
Q_{gc}			47		nC
$t_{d(on)}$	**Inductive Load, T_J = 25°C**		26		ns
t_{ri}	I_C = 44A, V_{GE} = 15V		41		ns
E_{on}	V_{CE} = 480V, R_G = 5Ω		1.30		mJ
$t_{d(off)}$	Note 2		155	335	ns
t_{fi}			95	165	ns
E_{off}			1.05	2.0	mJ
$t_{d(on)}$	**Inductive Load, T_J = 125°C**		26		ns
t_{ri}	I_C = 44A, V_{GE} = 15V		37		ns
E_{on}	V_{CE} = 480V, R_G = 5Ω		2.34		mJ
$t_{d(off)}$	Note 2		220		ns
t_{fi}			165		ns
E_{off}			2.20		mJ
R_{thJC}				0.375	°C/W
R_{thCS}			0.21		°C/W

TO-247 (IXGH) Outline



Dim.	Millimeter min	Millimeter max	Inches min	Inches max
A	4.70	5.30	0.185	0.209
A1	2.21	2.59	0.087	0.102
A2	1.50	2.49	0.059	0.098
b	0.99	1.40	0.039	0.055
b2	1.65	2.39	0.065	0.094
b4	2.59	3.43	0.102	0.135
c	0.38	0.89	0.015	0.035
D	20.79	21.45	0.819	0.845
D1	13.07	-	0.515	-
D2	0.51	1.35	0.020	0.053
E	15.48	16.24	0.610	0.640
E1	13.45	-	0.53	-
E2	4.31	5.48	0.170	0.216
e	5.45 BSC		0.215 BSC	
L	19.80	20.30	0.078	0.800
L1	-	4.49	-	0.177
Ø P	3.55	3.65	0.140	0.144
Ø P1	-	7.39	-	0.290
Q	5.38	6.19	0.212	0.244
S	6.14 BSC		0.242 BSC	

Reverse Diode (FRED)

Symbol	Test Conditions (T_J = 25°C Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
V_F	I_F = 30A, V_{GE} = 0V, Note 1			2.7	V
	T_J = 150°C		1.6		V
I_{RM}	I_F = 30A, V_{GE} = 0V, -di_F/dt = 100A/µs, T_J = 100°C			4	A
t_{rr}	V_R = 100V, T_J = 100°C		100		ns
	I_F = 1A, V_{GE} = 0V, -di_F/dt = 100A/µs, V_R = 30V		25		ns
R_{thJC}				0.9	°C/W

Notes:

1. Pulse test, t ≤ 300µs, duty cycle, d ≤ 2%.
2. Switching times & energy losses may increase for higher V_{CE}(clamp), T_J or R_G.

IXYS Reserves the Right to Change Limits, Test Conditions and Dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents: 4,835,592 4,860,072 4,881,106 4,931,844 5,017,508 5,034,796 5,049,961 5,063,307 5,187,117 5,237,481 5,381,025 5,486,715 6,162,665 6,259,123 B1 6,306,728 B1 6,404,065 B1 6,534,343 6,583,505 6,683,344 6,710,405 B2 6,710,463 6,727,585 6,759,692 6,771,478 B2 7,005,734 B2 7,063,975 B2 7,071,537 7,157,338B2

Fig. 1. Output Characteristics @ 25ºC

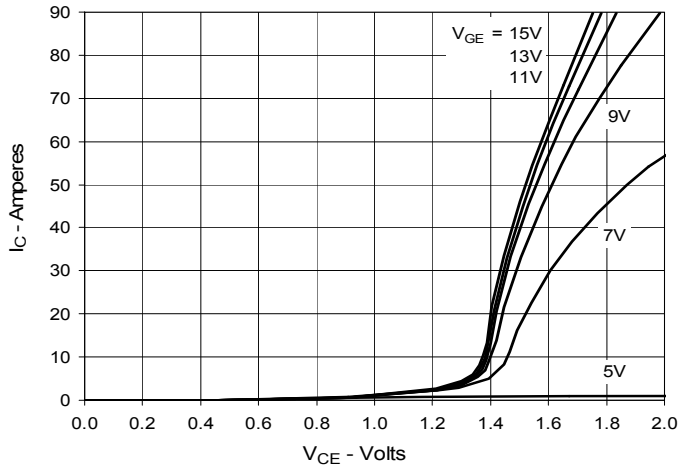


Fig. 2. Extended Output Characteristics @ 25ºC

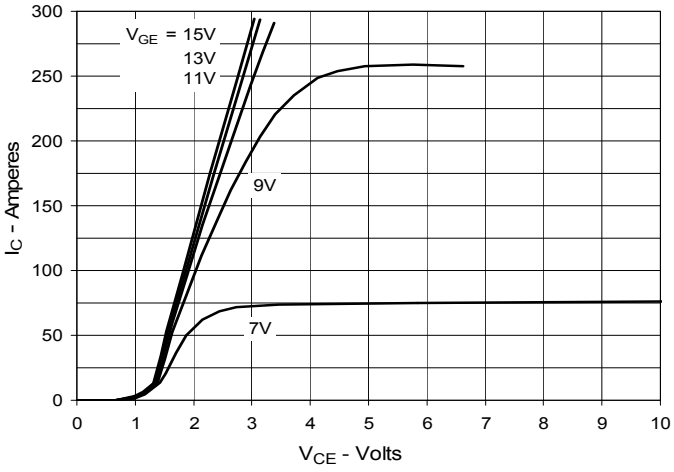


Fig. 3. Output Characteristics @ 125ºC

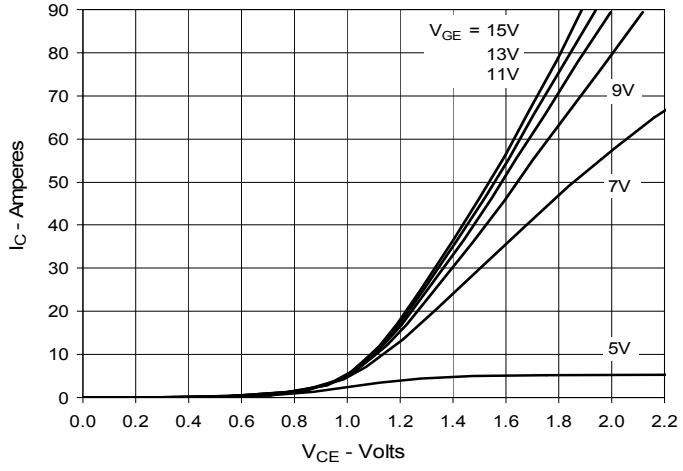


Fig. 4. Dependence of $V_{CE(sat)}$ on Junction Temperature

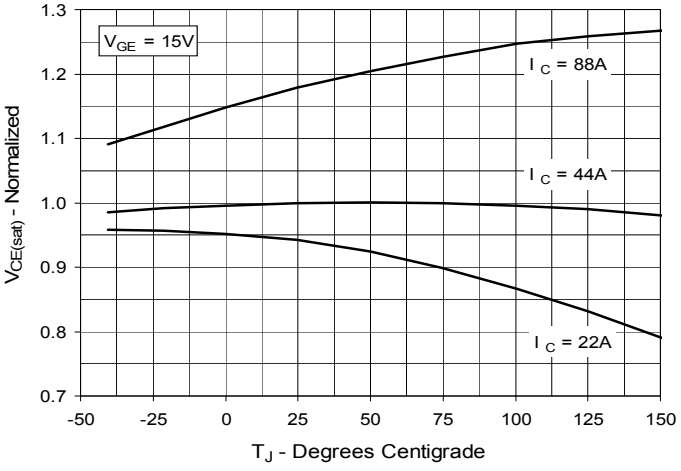


Fig. 5. Collector-to-Emitter Voltage vs. Gate-to-Emitter Voltage

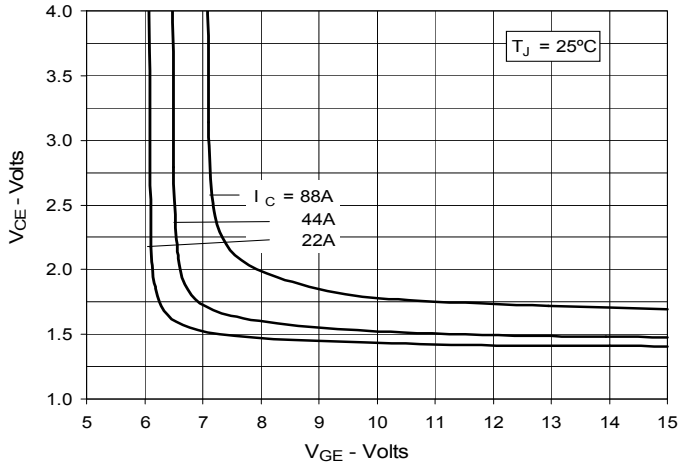
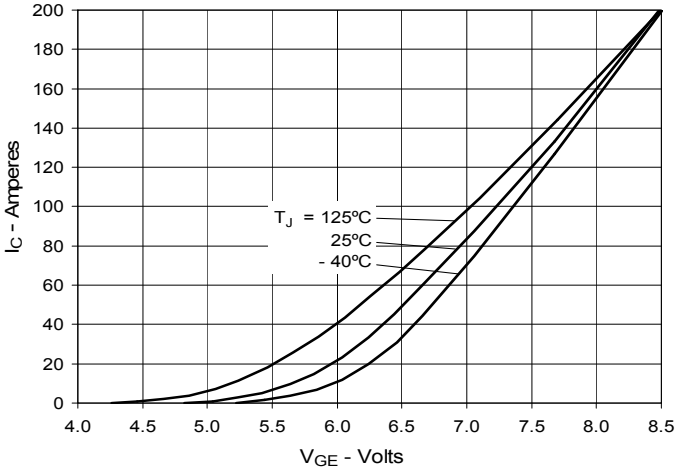


Fig. 6. Input Admittance



© 2014 IXYS CORPORATION, All Rights Reserved

Fig. 7. Transconductance

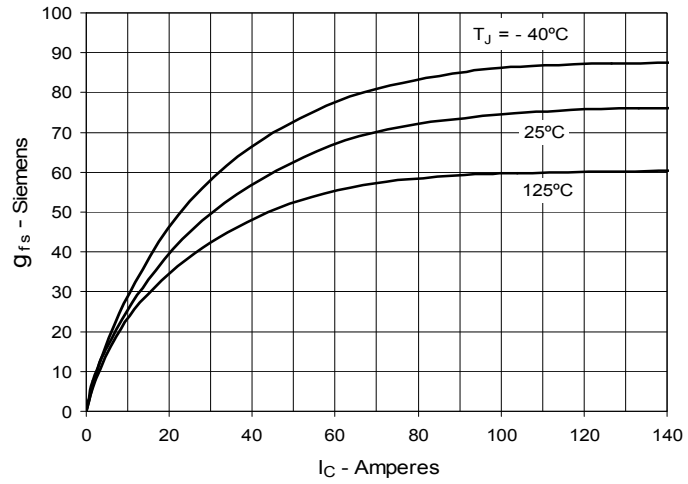


Fig. 8. Gate Charge

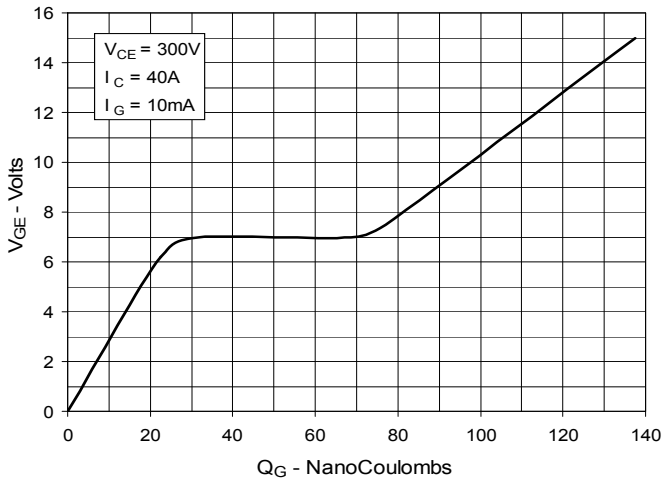


Fig. 9. Capacitance

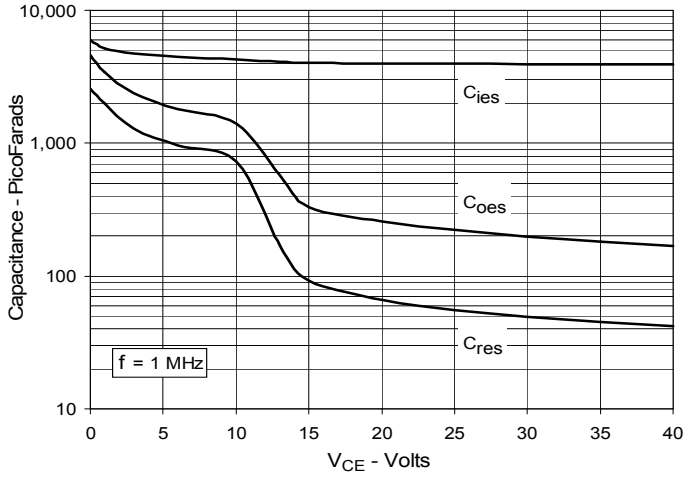


Fig. 10. Reverse-Bias Safe Operating Area

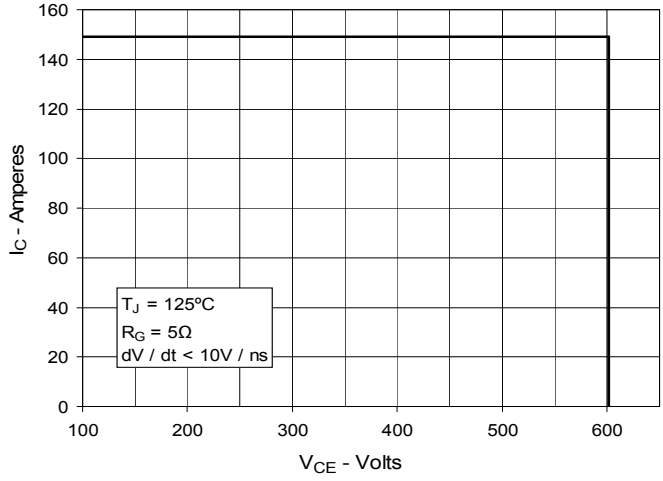
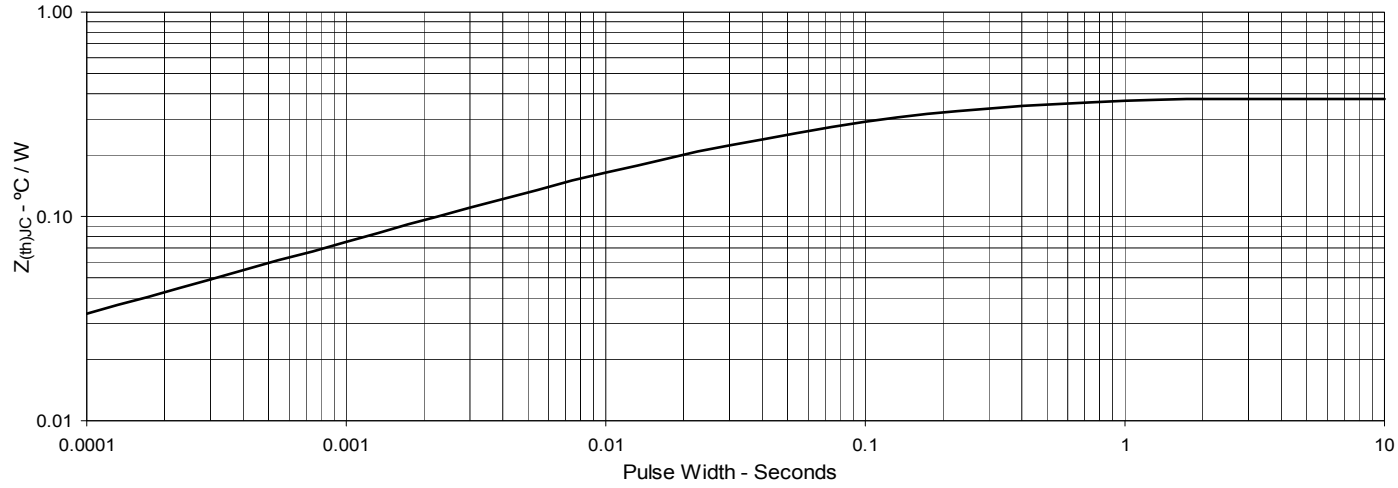


Fig. 11. Maximum Transient Thermal Impedance



IXYS Reserves the Right to Change Limits, Test Conditions and Dimensions.

Fig. 12. Inductive Switching Energy Loss vs. Gate Resistance

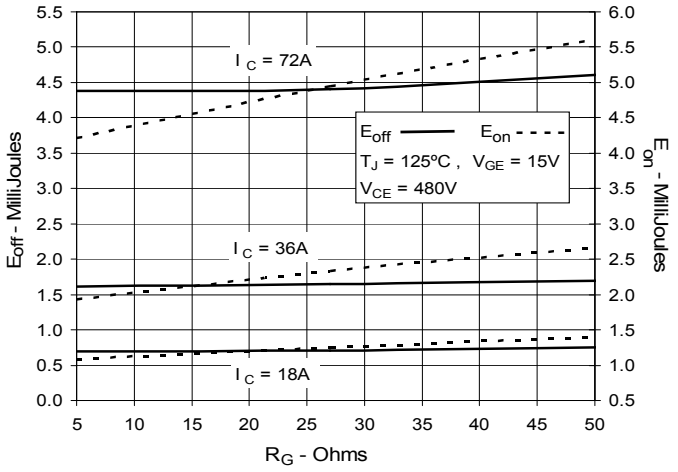


Fig. 13. Inductive Swiching Energy Loss vs. Collector Current

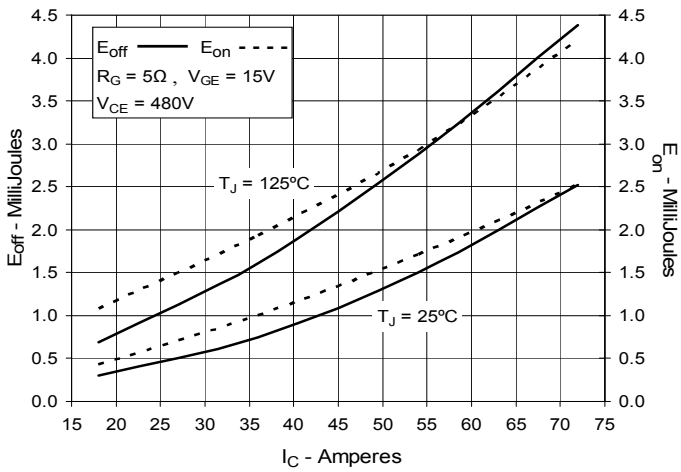


Fig. 14. Inductive Swiching Energy Loss vs. Junction Temperature

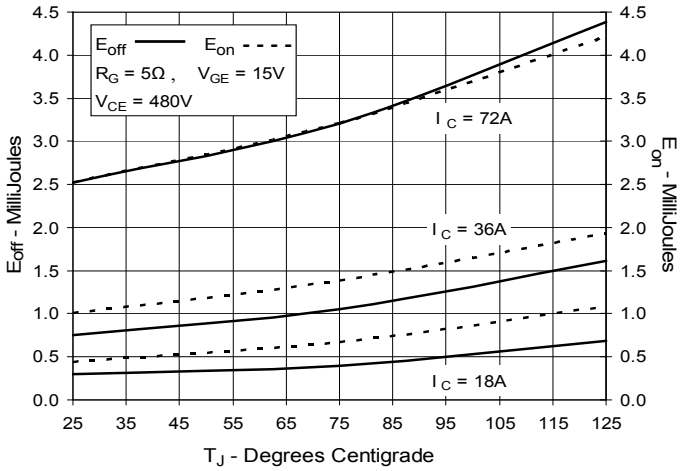


Fig. 15. Inductive Turn-off Switching Times vs. Gate Resistance

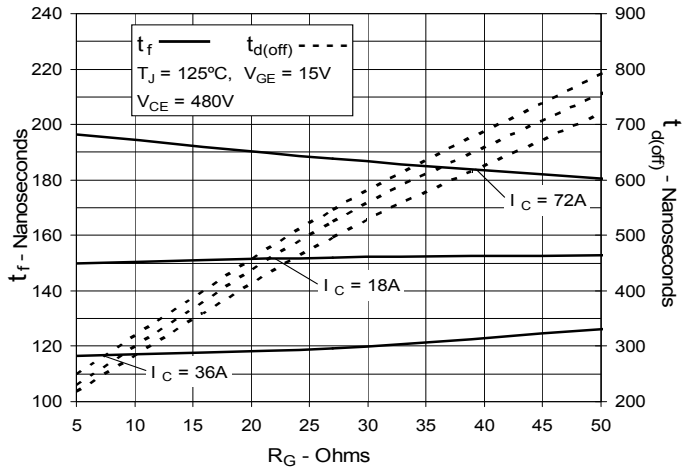


Fig. 16. Inductive Turn-off Switching Times vs. Collector Current

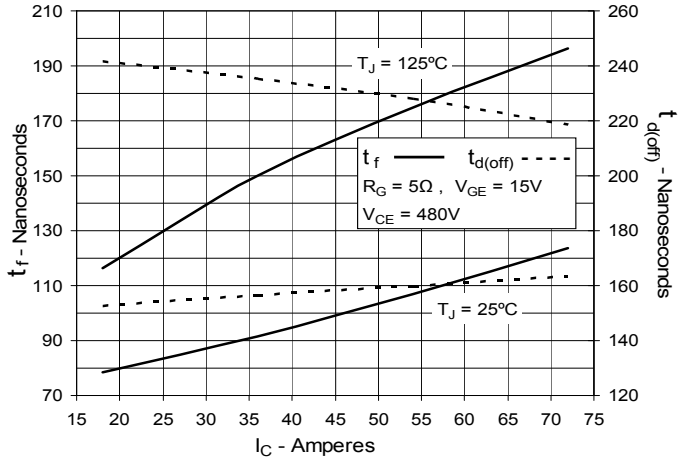
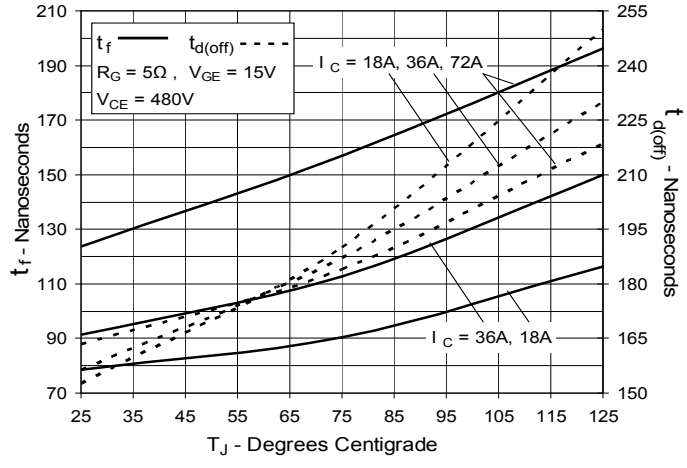


Fig. 17. Inductive Turn-off Switching Times vs. Junction Temperature



© 2014 IXYS CORPORATION, All Rights Reserved

Fig. 18. Inductive Turn-on Switching Times vs. Gate Resistance

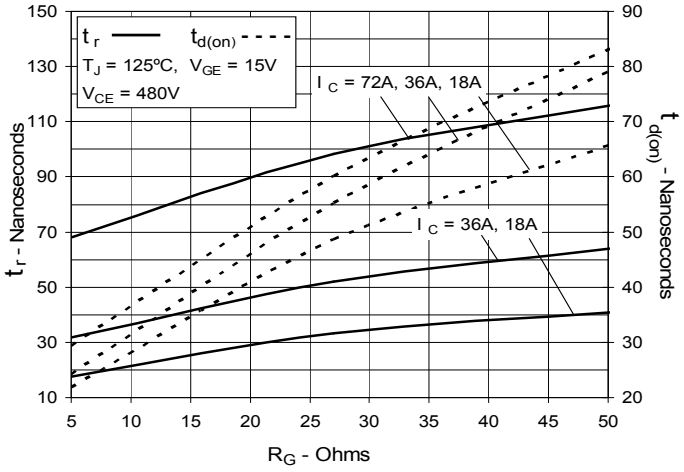


Fig. 19. Inductive Turn-on Switching Times vs. Collector Current

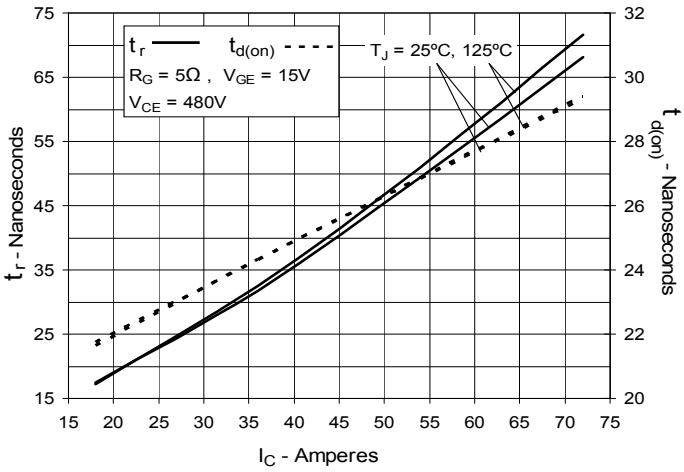
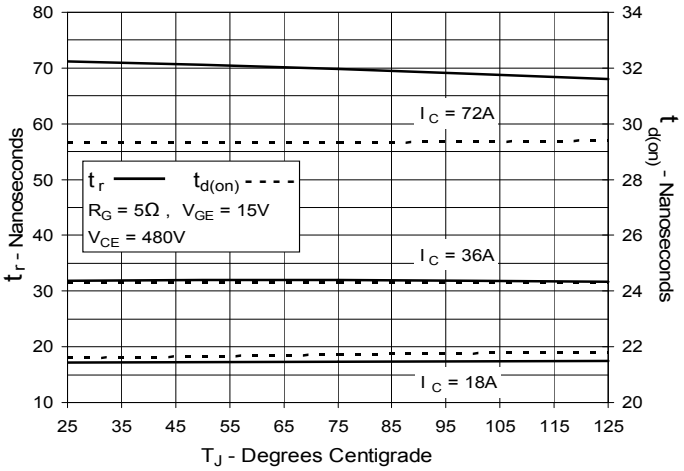


Fig. 20. Inductive Turn-on Switching Times vs. Junction Temperature



IXYS Reserves the Right to Change Limits, Test Conditions and Dimensions.

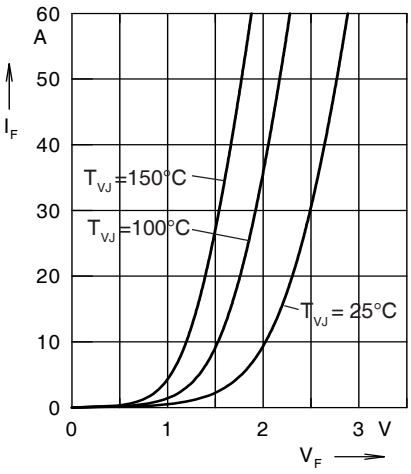


Fig. 21. Forward Current I_F Versus V_F

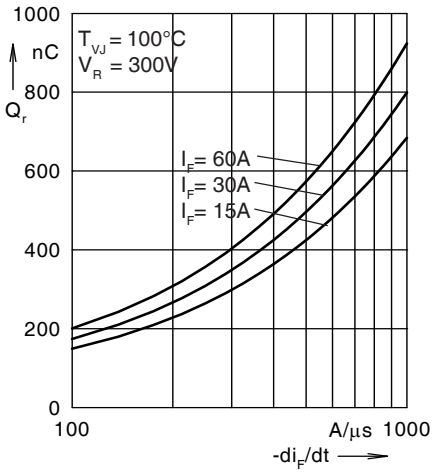


Fig. 22. Reverse Recovery Charge Q_r Versus $-di_F/dt$

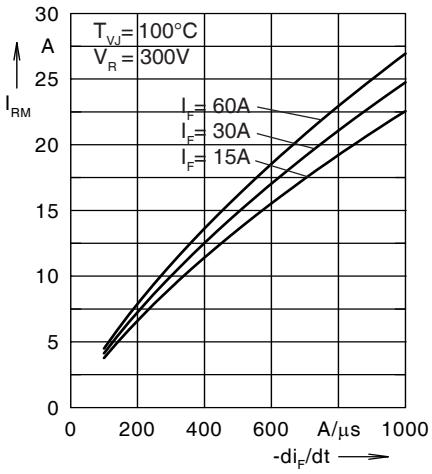


Fig. 23. Peak Reverse Current I_{RM} Versus $-di_F/dt$

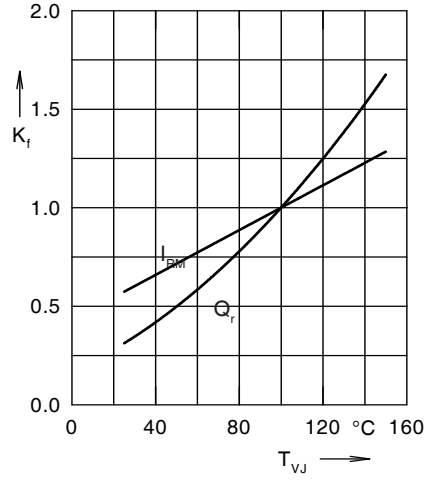


Fig. 24. Dynamic Parameters Q_r, I_{RM} Versus T_{VJ}

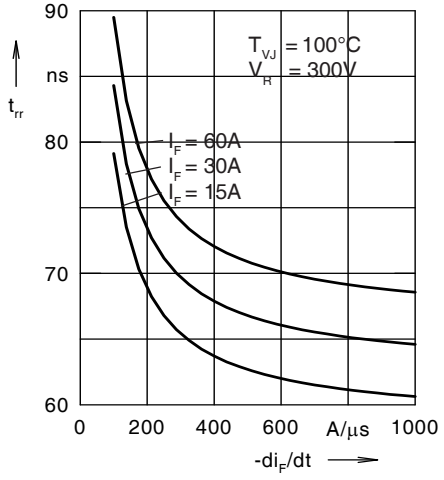


Fig. 25. Recovery Time t_{rr} Versus $-di_F/dt$

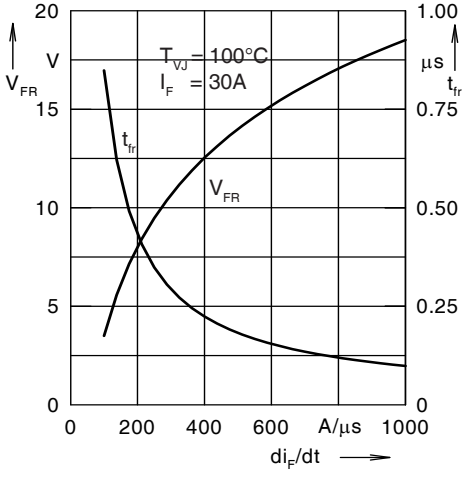


Fig. 26. Peak Forward Voltage V_{FR} and t_{fr} Versus di_F/dt

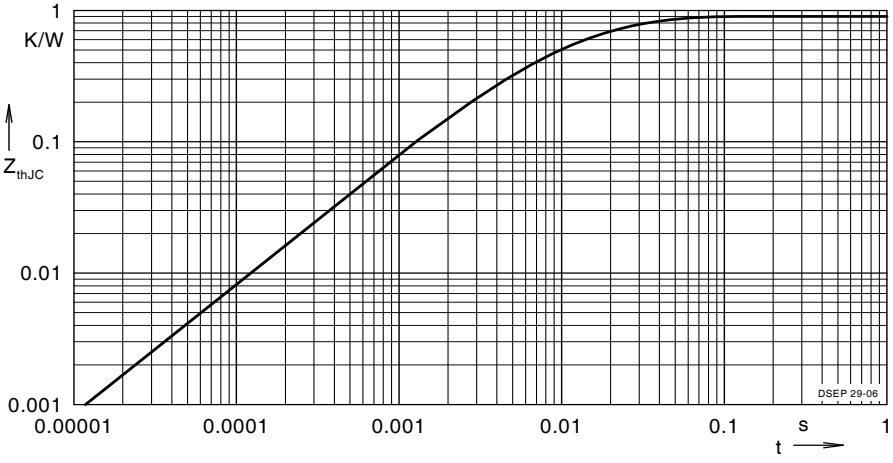


Fig. 27. Transient Thermal Resistance Junction to Case

Constants for Z_{thJC} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.502	0.0052
2	0.193	0.0003
3	0.205	0.0162

© 2014 IXYS CORPORATION, All Rights Reserved



Disclaimer Notice - Information furnished is believed to be accurate and reliable. However, users should independently evaluate the suitability of and test each product selected for their own applications. Littelfuse products are not designed for, and may not be used in, all applications. Read complete Disclaimer Notice at www.littelfuse.com/disclaimer-electronics.